

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wen-Chih CHIOU</td> <td>04/14/2010</td> </tr> <tr> <td>Weng-Jin WU</td> <td>04/14/2010</td> </tr> <tr> <td>Shau-Lin SHUE</td> <td>04/14/2010</td> </tr> </tbody> </table>		Name	Execution Date	Wen-Chih CHIOU	04/14/2010	Weng-Jin WU	04/14/2010	Shau-Lin SHUE	04/14/2010		
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI, Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300
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CORRESPONDENCE DATA											
Fax Number: 7035185499 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 7036841111 Email: tsmc@ipfirm.com Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC) Address Line 1: 2318 Mill Road Address Line 2: Suite 1400 Address Line 4: Alexandria, VIRGINIA 22314											
ATTORNEY DOCKET NUMBER:	T5057-Y117UB										
NAME OF SUBMITTER:	Randy A. Noranbrock										
Signature:	/Randy A. Noranbrock/										
Date:	04/17/2013										
Total Attachments: 1 source=efiledassgn#page1.tif											

OP \$40.00 13864676

Docket No.: T5057-Y117U

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Wen-Chih CHIOU
- 2) Weng-Jin WU
- 3) Shau-Lin SHUE

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan, R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

PROTECTION LAYER FOR ADHESIVE MATERIAL AT WAFER EDGE

(a) for which an application for United States Letters Patent was filed on 4-29-10, and identified by United States Patent Application No. 12/769,725; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Wen-Chih Chiou
Name: Wen-Chih CHIOU

4/14 '10
Date:

2) Weng-Jin Wu
Name: Weng-Jin WU

4/14 '10
Date:

3) Shau-Lin Shue
Name: Shau-Lin SHUE

4/14 '10
Date: